

All numerical values are in metric units [with U.S. customary units in brackets]. Dimensions are in millimeters. Unless otherwise specified, dimensions have a tolerance of ± 0.13 [$\pm .005$] and angles have a tolerance of $\pm 2^\circ$. Figures and illustrations are for identification only and are not drawn to scale.

1. INTRODUCTION

This specification covers the requirements for application of stacked QSFP-DD through bezel connector and cage assembly (with or without heatsink). The connector and cage assembly is available in a 2x1, 2x2 and 2x3 configuration. The cage assembly houses the connector and serves as a housing for the mating module. The optional heatsink are located top or middle chamber of the cage assembly and are used to dissipate heat from module to outer environment. The connector and cage assembly is designed to be mounted through a cutout in a bezel.

The right-angle Stacked QSFP-DD connector has 152 positions of compliant pins contacts with spacing on 0.80mm centerlines, 2 card entry slots that each accept a 1.0+0.1 thick integrated circuit card housed in the mating module.

The cage assembly is a frame with compliant pins contacts and front-perimeter electromagnetic interference (EMI) conductive metal EMI springs and internal EMI springs. Each cage assembly contact features a standoff that aids in proper seating of the cage assembly on the pc board. The cage assembly features 2 ports (for 2x1 configuration) or 4 ports (for 2x2 configuration) or 6 ports (for 2x3 configuration) that each port accept a mating module, 2 hard stops that controls the insertion depth of the mating modules, and locking latches that hold the installed mating modules in place. The EMI springs block any EMI emissions emanating from the mating module and the metal EMI spring provides EMI shielding for the system. The EMI/dust covers are used to confine EMI emissions and prevent contaminants from entering the cage assembly when mating modules are not installed. EMI/dust covers are available separately.

When corresponding with personnel, use the terminology provided in this specification to facilitate your inquiries for information. Basic terms and features of this product are provided in Figure 1.

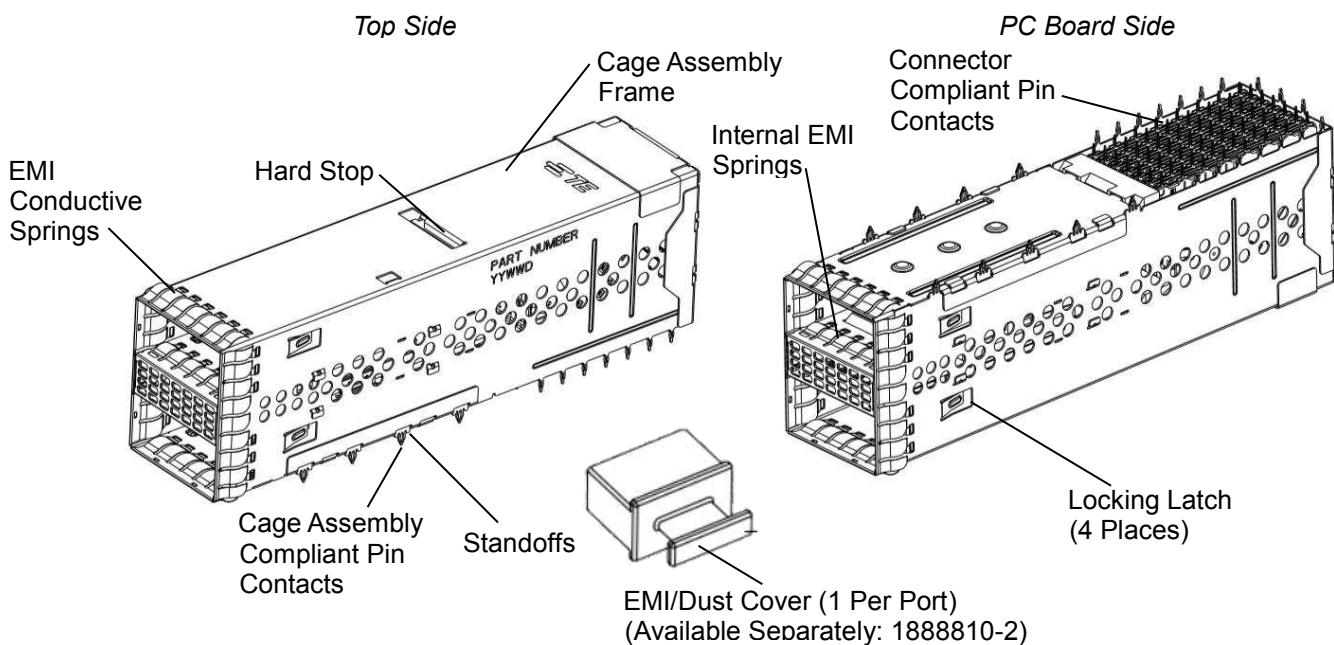


Figure 1

2. REFERENCE MATERIAL

2.1. Revision Summary

Revisions to this application specification include:

Revision 1

2.2. Customer Assistance

Reference the following Product Base Part Number and Product Code L818 are representative of stacked QSFP-DD through bezel connector and cage assembly (with or without heatsink). Use of these numbers will identify the product line and expedite your inquiries through a service network established to help you obtain product and tooling information. Such information can be obtained through a local Representative or, after purchase, by calling PRODUCT INFORMATION at the number at the bottom of page 1.

Product Series

Description

2329457-*	2x1 with Metal EMI Spring and Sloped HS
2361867-*	2x1 with Metal EMI Spring and TB HS
2339936-*	2x1 with Metal EMI Spring and top LP, BTB application
2339725-*	2x1 with Metal EMI Spring, close top and central zipper HS
2340483-*	2x1 with Metal EMI Spring, close top and central extrusion HS
2340397-*	2x1 with Metal EMI Spring, standard version with zipper HS
2343246-*	2x1 with Metal EMI Spring, standard version with extrusion HS
2358410-*	2x2 with Metal EMI Spring,
2358411-*	2x3 with Metal EMI Spring,

2.3. Drawings

Customer Drawings for product part numbers are available from the service network. If there is a conflict between the information contained in the Customer Drawings and this specification or with any other technical documentation supplied, the drawing information takes precedence or call PRODUCT INFORMATION at the number at the bottom of page 1.

2.4. Specifications

Design Objective 108-60130 provides expected product performance and test information.

2.5. Instructional Material

Instruction Sheets (408-series) provide product assembly instructions or tooling setup and operation procedures. Documents available that pertain to this product are:

- 408-6923 Manual Arbor Frame Assembly 58024-1
- 408-32237 Stacked QSFP-DD Extraction Tool Kit
- 408-35098 Stacked QSFP-DD Seating Tool Kit

3. REQUIREMENTS

3.1. Safety

Do not stack product shipping containers so high that the containers buckle or deform.

3.2. Limitations

The requirements given for the bezel are specifically configured for products used in the communications industry and PCI applications.

3.3. Material

The connector housing and chicklets (part that holds the compliant pin contacts) are made of molded thermoplastic, UL 94-V-0. All compliant pin contacts are made of copper alloy underplated with nickel and plated with tin at the leads and gold or palladium nickel at the interface area. The cage assembly is made of stainless steel. The EMI/dust cover is made of die cast zinc. The light pipes are made of clear polycarbonate. The heatsinks are made of Aluminum or copper.

3.4. Storage

The connector and cage assembly should remain in the shipping containers until ready for use to prevent deformation to the contacts. Product should be used on a first in, first out basis to avoid storage contamination that could adversely affect performance.

3.5. Chemical Exposure

Do not store product near any chemical listed below as they may cause stress corrosion cracking in the contacts.

Alkalies	Ammonia	Citrates	Phosphates	Citrates	Sulfur Compounds
Amines	Carbonates	Nitrites	Sulfur Nitrites		Tartrates

3.6. Host PC Board

A. Material and Thickness

The host pc board material shall be glass epoxy (FR-4 or G-10). The thickness shall be a minimum of 1.57.

i **NOTE**
Contact **PRODUCT INFORMATION** at the number listed at the bottom of page 1 for suitability of other pc board materials.

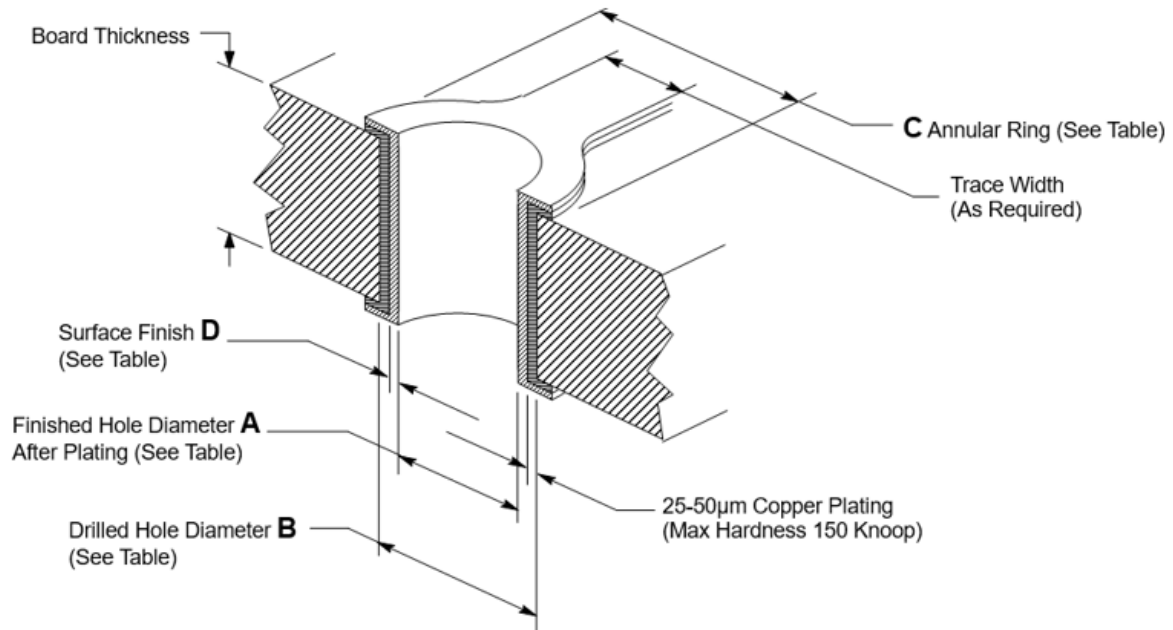
B. Tolerance

Maximum allowable bow of the pc board shall be 0.08 over the length of the connector and cage assembly.

C. Holes

The holes for the compliant pin contact must be drilled and plated through to dimensions specified in Figure 2. Refer to appropriate Customer Drawing for PCB Hole designation; also shown in Figure 3- Sample PCB.

PC Board Contact Holes



DIM. "A"	DIM. "B"	DIM. "C"	DIM. "D"	
FINISHED HOLE DIAMETER (After Plating)	DRILLED HOLE DIAMETER	ANNULAR RING DIAMETER	SURFACE FINISH	THICKNESS
0.31±0.05	0.39±0.020	0.66±0.05	Immersion Tin (Sn)	0.0005 Min
0.56±0.05	0.66±0.020	0.91±0.05	Organic Solderability Preservative (OSP)	0.0002-0.0005
1.05±0.05	1.15±0.020	1.40±0.05	Immersion Silver (Ag)	0.0001-0.0005
			Immersion Gold (Au) Over Nickel (Ni) (ENIG)	0.004-0.0076 (Ni) 0.0001-0.0005 (Au)

Figure 2

D. Layout

The holes for the connector and cage assembly must be precisely located to ensure proper placement and optimum performance. Recommended hole pattern, dimensions, and tolerances are provided on the Customer Drawing for the specific connector and cage assembly. Sample layout is provided in Figure 3.

Connector board routing recommendations please refer to TE QSFP DD stacked routing guide.

3.7. Bezel

A. Thickness

The bezel thickness range shall be 0.8 through 2.6.

B. Cutout

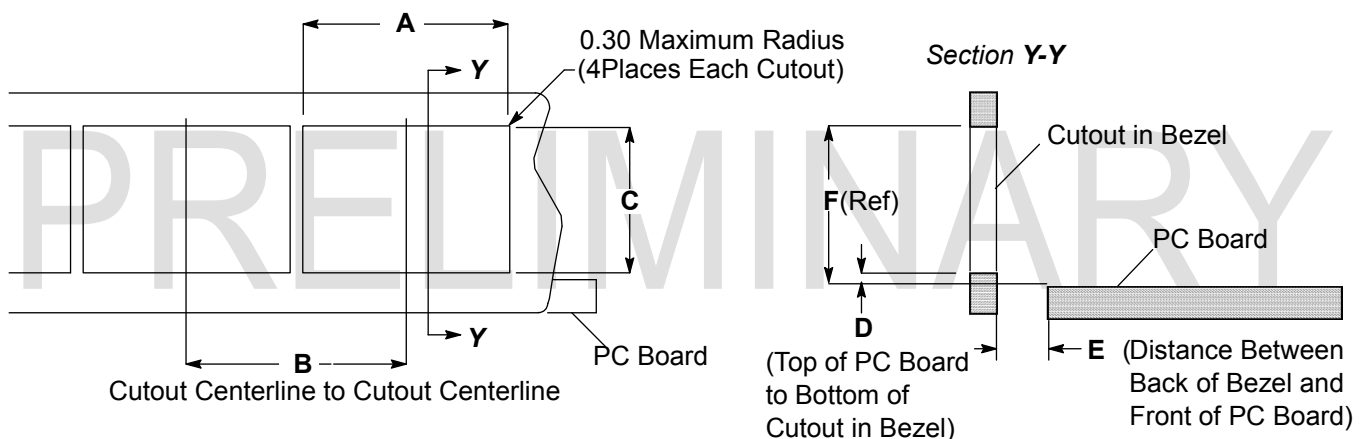
The bezel must provide a cutout that allows proper mounting of the connector and cage assembly. The cage assembly EMI springs must be compressed by the bezel in order to provide an electrical ground between the connector and cage assembly and bezel for EMI suppression.

Care must be used to avoid interference between adjacent connector and cage assemblies and other components. The minimum allowable distance between connector and cage assemblies must be considered to ensure proper assembly. Dimensions for bezel cutout and minimum allowable distance between cutouts are shown in Figure 4.

C. PC Board and Bezel Position

The bezel and pc board must be positioned in relation to each other to avoid interference with the function of the cage assembly locking latches and to ensure proper function of the EMI springs. This relationship must conform to the dimensions given in Figure 4.

Recommended Bezel Cutout (Minimum Pitch) and PC Board and Bezel Position



Note: Not to Scale

CAGE ASSEMBLY CONFIGURATION	DIMENSION (With Metal EMI Spring Gasket)					
	A ±0.10	B (Min)	C ±0.10	D ±0.10	E ±0.13	F (Ref)
2 x 1 Ganged	20.50	22.00	25.70	0.10	3.02	25.8
2 x 2 Ganged	39.50	41.00	25.70	0.10	3.02	25.8
2 x 3 Ganged	58.50	60.00	25.70	0.10	3.02	25.8

Figure 4(End)

3.8. Installing Connector and Cage Assembly on PC Board

A. Placement

The compliant pin contacts and alignment posts (connector only) must be aligned with matching holes in the pc board, then inserted into the pc board simultaneously to prevent twisting or bending of these parts.

B. Seating

Using proper seating force and seating height is essential to interconnection performance. The force used to seat the connector and cage assembly must be applied evenly to prevent deformation or other damage

to the compliant pin contacts and alignment posts. The force required to seat the connector and cage assembly onto the pc board can be calculated by:

$$\text{Amount of Cage Assembly Compliant Pin Contacts } 44.5 \text{ N [10 lb-force] (Force per Contact) +} \\ \text{Connector Compliant Pin Contacts } 20 \text{ N [4.5 lb-force] (Force per Contact) = Seating Force}$$



Over-driving of the connector and cage assembly will deform parts critical to the quality of the connection. Maximum force occurs prior to the connector and cage assembly bottoming on the pc board.

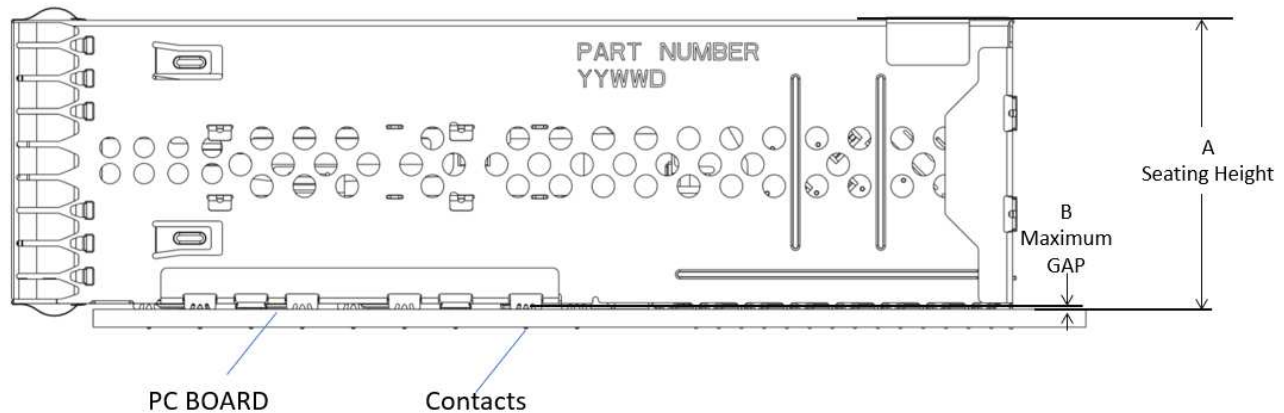
The shut height of the application tool must be specifically set for proper seating of the connector and cage assembly. The shut height can be calculated by:

$$\text{Seating Height (Connector and Cage Assembly Seated) + Height of Seating Tool +} \\ \text{Combined Thicknesses of PC Board and PC Board Support Fixture = Shut Height (Ram Down)}$$



The seating height, measured from the top of the cage assembly (not including the EMI springs or elastomeric gasket) to the top of the pc board, given in Figure 5, may need to be adjusted to maintain the maximum gap between the bottom of the cage assembly standoff and the pc board.

The contacts must be inserted into the holes in the pc board until the bottom of the cage assembly contact standoffs are seated on the pc board. The alignment posts of the connector must be through the holes in the pc board. The connector and cage assembly must be seated on the pc board not exceeding the dimensions given in Figure 5.



DIMENSION A (Top of Cage Assembly, Not Including EMI Springs or Elastomeric Gasket, to PC Board)	DIMENSION B (Bottom of Cage Assembly Standoffs to PC Board)
25.4	0.10

Figure 5

3.9. Mounting in Bezel

The cage assembly EMI springs must be compressed by the bezel. A slight bow in the cage assembly is permitted. The mating face of the cage assembly must be centered in the bezel cutout. It is recommended that the distance from the top of the bezel cutout to the pc board meet the dimension given in Figure 6.

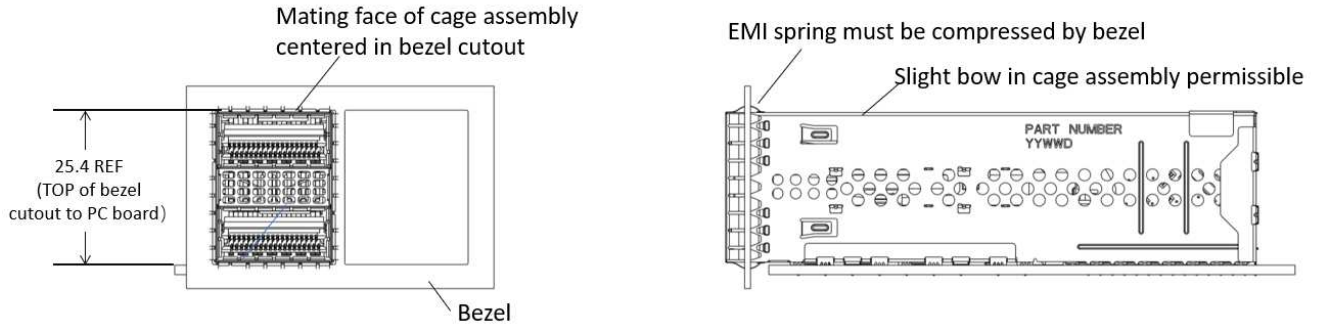


Figure 6

3.10. EMI/Dust Cover

An EMI/dust cover must be fitted into each port of the cage assembly when the connector and cage assembly is not mated to the module.

3.11. Replacement and Repair

Damaged or defective connector and cage assemblies must be removed and replaced. If repair or rework to the pc board requires soldering after the connector and cage assembly has been seated onto the pc board, the following must apply:

- After soldering, removal of fluxes, residues, and activators is necessary. Consult with the supplier of the solder and flux for recommended cleaning solvents. Cleaners must be free of dissolved flux and other contaminants. Even when using a "no clean" solder paste, it is imperative that the contact interface be kept clean of flux and residue (since it acts as an insulator).



Consideration must be given to toxicity and other safety requirements recommended by the solvent manufacturer. Refer to the manufacturer's Material Safety Data Sheet (MSDS) for characteristics and handling of cleaners. Trichloroethylene and methylene chloride is not recommended because of harmful occupational and environmental effects. Both are carcinogenic (cancer-causing).

- Air drying is recommended. Otherwise, temperature limitations must not exceeded: -55° to 105°C [-67° to 221°F]. Excessive temperatures may cause housing degradation.

After extraction, the connector and cage assembly should not be re-used.

4. QUALIFICATION

No outside agency approvals for stacked QSFP-DD connector and cage assembly (with metal EMI spring gasket) was defined at the time of publication of this document.

5. TOOLING

Tooling part numbers and instructional material packaged with the tooling are given in Figure 7.

5.1. Seating Tool

The seating tool is used to seat the connector and cage assembly onto the pc board. The seating tool is available in a kit, which contains a wall support used to support the individual ports of the cage assembly.

5.2. Extraction Tool

The extraction tool is used to remove the connector and cage assembly from the pc board by pushing the pc board off of the connector and cage assembly. The extraction tool is available in a kit, which includes a wall support used to support the individual ports of the cage assembly.

5.3. Application Tool

Power for the seating tool and extraction tool must be provided by an application tool (with a ram) capable of supplying a downward force of 44.5 N [10 lb-force] per cage assembly contact and 20 N [4.5 lb-force] per connector contact. The manual arbor frame assembly is available for use with these tools.

5.4. PC Board Support Fixture

A pc board support must be used with the seating tool and the extraction tool. The support fixture provides proper support for the pc board and protects the pc board and the connector and cage assembly from damage. The support fixture must be customer designed. It is recommended that the support fixture be at least 25.4 longer and wider than the pc board and have flat surfaces with holes or a channel large enough and deep enough to receive any protruding components of the connector and cage assembly.

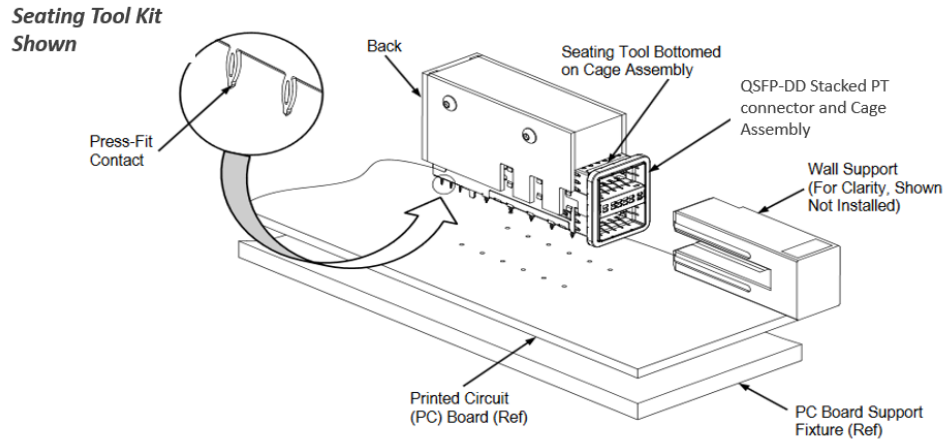


Figure 7

6. VISUAL AID

The illustration below shows a typical application of stacked zQSFP+Stacked connector and through bezel cage assembly (with or without light pipes). This illustration should be used by production personnel to ensure a correctly applied product. Applications which DO NOT appear correct should be inspected using the information in the preceding pages of this specification and in the instructional material shipped with the product or tooling.

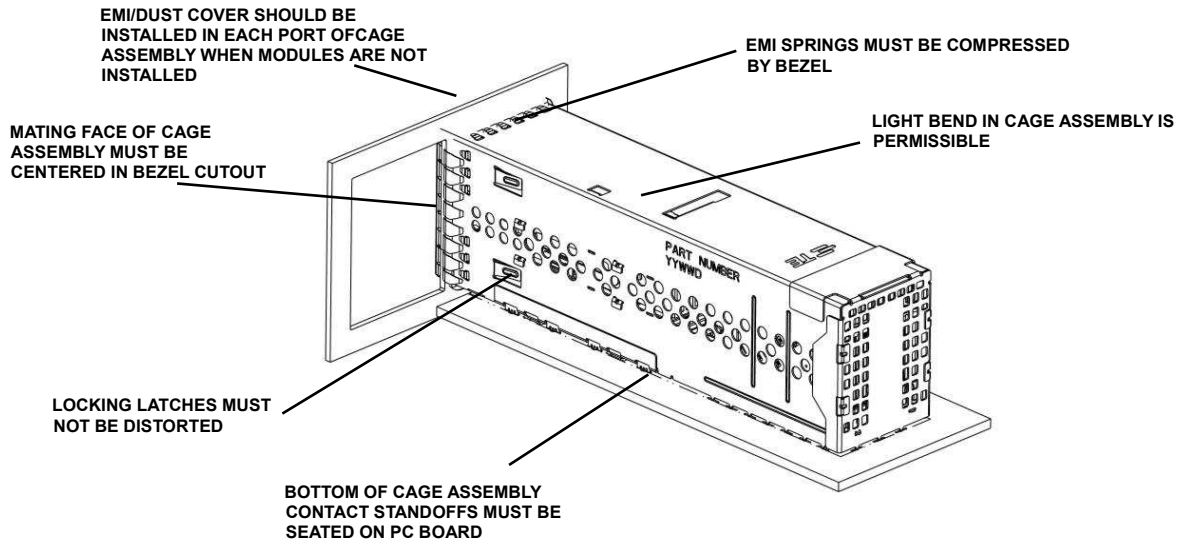


FIGURE 8. VISUAL AID